



## UF6803

**PRODUCT DESCRIPTION**

UF6803 provides the following product characteristics:

Technology	Epoxy
Chemical Type	Epoxy
Appearance	Opaque cream yellow liquid
Cure	Heat cure
Cure Benefit	Production - high speed curing
Application	Underfill
Specific Application	Reworkable underfill for CSP (FBGA) or BGA
Dispense Method	Syringe
Key Substrates	SMD components to PCB
Reworkable	Yes

UF6803 is a single component, epoxy adhesive designed for use as a reworkable underfill resin for CSP(FBGA) or BGA. It cures rapidly on exposure to heat. It is designed to give excellent protection from failure due to mechanical stress. The low viscosity allows filling in gaps under CSP or BGA.

**TYPICAL PROPERTIES OF UNCURED MATERIAL**

Specific Gravity @ 25 °C	1.1
Viscosity, Cone & Plate, mPa·s (cP), Temperature: 25 °C, Shear Rate: 36 s <sup>-1</sup>	4,000
Pot life @ 22 °C, hours	48
Flash Point - See MSDS	

**Recommended Curing Conditions**

15 minutes @ 120 °C

**Note:** With all fast cure systems, the time required for cure depends on the rate of heating. Conditions where a hot plate or heat sink is used are optimum for fastest cure. Cure rates depend on the mass of material to be heated and intimate contact with the heat source. Use suggested cure conditions as general guidelines. Other cure conditions may yield satisfactory results.

**TYPICAL PROPERTIES OF CURED MATERIAL**

Cured for 60 minutes @ 100 °C

**Physical Properties:**

Density @ 25 °C, g/cm <sup>3</sup>	1.1
Shrinkage, %	2.5
Shore Hardness, ISO 868, Durometer D	86
Glass Transition Temperature, °C: (T <sub>g</sub> ) by DMTA	69
Coefficient of Thermal Expansion, ASTM D 3386, K :	
Pre T <sub>g</sub> (Alpha 1) <sup>-1</sup>	63×10 <sup>-6</sup>
Post T <sub>g</sub> (Alpha 2)	210×10 <sup>-6</sup>
Coefficient of Thermal Conductivity ASTM E 1530, W/(m·K)	0.2
Water Absorption, ISO 62, %: 24 hours in water @ 25 °C	0.16
Elongation, at break, ISO 527-3, %	3.6
Tensile Strength, at break, ISO 527-3	N/mm <sup>2</sup> 56

Tensile Modulus, ISO 527-3	(psi) (8,120)
	N/mm <sup>2</sup> 2,200
	(psi) (319,100)

**Electrical Properties:**

Dielectric Constant / Dissipation Factor, IEC 60250:

100-kHz	3.6 / 0.016
1-MHz	3.5 / 0.017
10-MHz	3.5 / 0.024

Volume Resistivity, IEC 60093, Ω·cm

4.4×10<sup>16</sup>

Surface Resistivity, IEC 60093, Ω

1.1×10<sup>16</sup>

Dielectric Breakdown Strength,

16

IEC 60243-1, kV/mm

Surface Insulation Resistance, Ω:

IPC TM 650 2.6.3.1:

Test Board: IPC-B-25A, comb pattern D:

Initial 52×10<sup>12</sup>

Aged for 96 hours @ 85 °C, 85 % RH 8.1×10<sup>13</sup>

5 DCV loaded

**TYPICAL PERFORMANCE OF CURED MATERIAL****Adhesive Properties**

Cured for 60 minutes @ 100 °C

Lap Shear Strength, ISO 4587:

Steel (grit blasted)	N/mm <sup>2</sup> ≥8
	(psi) (≥1,160)
Epoxyglass	N/mm <sup>2</sup> 10
	(psi) (1,450)

**GENERAL INFORMATION**

**For safe handling information on this product, consult the Material Safety Data Sheet (MSDS).**

**Handling Information****1. Receiving Cold Shipments**

All shipping boxes are packed with cold gel packs to maintain temperature below 8 °C during transit.

**2. Temperature Equilibration**

A new package of material can be brought to ambient conditions by allowing to stand at room temperature (22±2 °C) for 1 to 2 hours (actual time required will vary with package size / volume).

Do not loosen container lids, caps or covers: syringe packs must be allowed to equilibrate in tip down orientation. Heat must never be used as partial polymerization (curing) could occur.

**Directions for use:**

Load product into dispensing equipment. A variety of application equipment types are suitable and include: hand dispense / time pressure valve; auger style valve; linear piston pump and jet valve. Selection of equipment should be determined by application requirements - for advice on equipment selection and process optimization, users should contact their Technical Service Center.

1. Ensure that air is not introduced to product during equipment set-up.

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2. For best results, the substrate should be preheated (typically to 40 °C for about 20 seconds) to allow fast capillary flow and facilitate leveling.
  3. Dispense product at moderate speed (2.5 to 12.7 mm/s). Ensure that needle tip is about 0.025 to 0.076 mm from substrate surface and from chip edge - this will ensure optimal flow conditions for the Underfill.
  4. The dispense pattern is typically "I" along one side or "L" pattern along two sides, focused at the corner. Application should start at the location furthest away from the chip center - this helps ensure a void free fill underneath the die. Each leg of the "L" or "I" pattern should not exceed 80 % of the length of each die edge being dispensed.
  5. In some cases second or third application of product may be necessary.

#### **For Rework**

##### **1. Removal of CSP from PCB**

Any instrument capable of melting solder is suitable for removing the CSP in this step.

When a sufficiently high temperature has been reached, touch the fillet of underfill around the CSP using a scraper to see if it is softened. If the fillet is soft enough, remove the fillet.

When bondline reaches temperature above melting point of solder, indicated by molten solder blowing out between CSP & PCB, remove the CSP from the PCB with a scraper.

##### **2. Removing Underfill Residue from PCB**

After removing the CSP, scrape away underfill and solder residues on the surface of the PCB using the Soldering Iron.

Typically recommendation of iron top temperature is 250 to 300 °C (setting temperature). Scraping of residue should be carefully executed to avoid damaging resist and pads on PCB.

##### **3. Clean Up**

Wipe the surface using a cotton swab soaked with a suitable solvent (e.g. 7360 or acetone).

Repeat this step with a clean dry cotton swab.

#### **Storage**

Store product in the unopened container in a dry location. Storage information may be indicated on the product container labeling.

**Optimal Storage: 2 °C to 8 °C. Storage below 2 °C or greater than 8 °C can adversely affect product properties.**

Material removed from containers may be contaminated during use. Do not return product to the original container. Longain Corporation cannot assume responsibility for product which has been contaminated or stored under conditions other than those previously indicated. If additional information is required, please contact your local Technical Service Center or Customer Service Representative.

**Do Not return product to refrigerated storage; any surplus product should be discarded**

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